What is claimed is:

- 1. A projection objective for microlithography having a lens arrangement comprising:
 - a first lens group having positive power;
 - a second lens group having negative power;
 - a third lens group having positive power;
 - a fourth lens group having negative power;
 - a fifth lens group having positive power; and
 - a sixth lens group having positive power;

wherein a lens at the end of said second lens group, or a lens at the beginning of said third lens group, has an aspheric surface.

- 2. The projection objective according to claim 1, wherein said lens at the end of said second lens group is the last lens of the second lens group.
- 3. The projection objective according to claim 1, wherein said lens at the beginning of said third lens group is the first lens of said third lens.
- 4. The projection objective according to claim 1, wherein said lens arrangement has only one lens having an aspheric surface.
- 5. A projection objective having a lens arrangement having at least a first waist of a pencil of rays, wherein said lens arrangement comprises at least one of the following:
 - a lens having an aspheric surface arranged before said first waist,
 - a lens having an aspheric surface arranged after said first waist, and
 - lenses having aspheric surfaces arranged before and after said first waist.

- 6. The projection objective according to claim 5, wherein at least two spherical lenses are arranged between said lenses having aspheric surfaces.
- 7. The projection objective according to claim 5, wherein said lens arrangement has a first lens group having positive power, a second lens group having negative power, a third lens group having negative power, a fourth lens group having negative power, and a fifth and sixth lens group respectively having positive power, wherein said first lens group has a lens having an aspheric surface.
- 8. The projection objective according to claim 6, wherein a lens having an aspheric surface is arranged in said second lens group before said waist.
- 9. The projection objective according to claim 7, wherein said third lens group has a lens having an aspheric surface.
- 10. The projection objective according to claim 7, wherein said second lens group has an aspheric surface arranged after said waist.
- 11. The projection objective according to claim 1, wherein said sixth lens group has a first lens having an aspheric surface.
- 12. The projection objective according to claim 1, wherein a last lens of said third lens group has an aspheric surface.
- 13. The projection objective according to claim 1, wherein said lens arrangement does not exceed a maximum lens diameter of 280 mm.
- 14. The projection objective according to claim 13, wherein said lens arrangement does not exceed a maximum lens diameter of 250 mm.

- 15. The projection objective according to claim 1, having an object side and an image side, wherein said lens arrangement has on said image side a numerical aperture of at least 0.75.
- 16. The projection objective according to claim 15, wherein said lens arrangement has on said image side a numerical aperture of 0.8.
- 17. The projection objective according to claim 1, wherein said lens arrangement comprises at least two different materials.
- 18. The projection objective according to claim 17 wherein said different materials comprise quartz glass and a fluoride or two fluorides.
- 19. The projection objective according to claim 8, further comprising an aperture stop wherein at least a last two positive lenses before said aperture stop are comprised of CaF₂.
- 20. The projection objective according to claim 1, wherein said lens arrangement comprises a positive lens comprised of CaF₂, followed by a negative lens of quartz glass, for formation of an achromat.
- 21. The projection objective according to claim 1, wherein said sixth lens group comprises a lens of CaF₂.
- 22. A refractive microlithographic projection objective, having a lens arrangement comprising at least one lens with an aspheric lens surface, wherein all aspheric lens surfaces have a vertex radius (R) of at least 300 mm.
- 23. The refractive microfichographic projection objective according to claim 19, wherein said vertex radius(R) is 350-1,000 mm.
- 24. The refractive microlithographic objective according to claim 19, wherein said vertex

radius (R) is greater than 1,000 mm.

- 25. The projection objective for microlithography according to claim 1, wherein the diameter said lens having an aspheric surface is smaller than 90% of the maximum diameter of said lens arrangement.
- 26. The projection objective according to claim 25, wherein the diameter of said lens having an aspheric surface is smaller than 80% of the maximum diameter of said lens arrangement.
- 27. A projection exposure device for microlithography, comprising a projection objective according to claim 1.
- 28. A projection exposure device for microlithography, comprising an excimer laser light source emitting radiation of wavelength shorter than 250 nm, and a projection objective according to claim 19.
- 29. The projection objective comprising a lens arrangement according to claim 1, wherein said lens arrangement has a high numerical aperture on an objective output side, and all lenses of said lens arrangement have sine values of all angles of incidence of radiation striking a respective lens that are always smaller than the numerical aperture of said lens arrangement.
- 30. The projection objective according to claim 29, wherein said numerical aperture is in the region of 0.85.
- The projection objective comprising a lens arrangement according to claim 1, wherein the maximum diameter of lenses of said third lens group is at least 10% smaller than the maximum diameter of lenses of said fifth lens group.
- 32. The projection objective comprising a lens arrangement according to claim 1, wherein at

least one aspheric lens surface is acted on with an angle loading of at least $\sin i = 0.75$.

33. A process for the production of microstructured components, comprising: exposing a substrate provided with a photosensitive layer with ultraviolet light by means of a mask and a projection exposure device with a lens arrangement according to claim 1, and,

if necessary after development of said photosensitive layer, structuring said substrate corresponding to a pattern contained on said mask.